

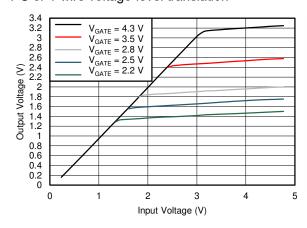
# TXS0104E-Q1 Automotive 4-Bit Bidirectional Voltage-Level Translator for Open-Drain and Push-Pull Applications

#### 1 Features

- Qualified for automotive applications
- AEC-Q100 qualified with the following results:
  - Device temperature grade 1: –40°C to +125°C ambient operating temperature range
  - Device HBM ESD Classification Level 2
  - Device CDM ESD Classification Level C6
- No direction-control signal required
- Maximum data rates:
  - 24 Mbps maximum (push pull)
  - 2 Mbps (open drain)
- 1.65 V to 3.6 V on A port and 2.3 V to 5.5 V on B port ( $V_{CCA} \leq V_{CCB}$ )
- No power-supply sequencing required—V<sub>CCA</sub> or V<sub>CCB</sub> can be ramped first
- ESD protection exceeds JESD 22:
  - A Port
    - 2000-V Human-Body Model (A114-B)
    - 1000-V Charged-Device Model (C101)
  - - 15-kV Human-Body Model (A114-B)
    - 1000-V Charged-Device Model (C101)
- IEC 61000-4-2 ESD (B port)
  - ±8-kV Contact Discharge
  - ±10-kV Air-Gap Discharge

# 2 Applications

- Automotive infotainment, advance driver assistance systems (ADAS)
- Isolates and level translates between main processor and peripheral modules
- I<sup>2</sup>C or 1-wire voltage-level translation



Transfer Characteristics of an N-Channel **Transistor** 

## 3 Description

The TXS0104E-Q1 device connects an incompatible logic communication from chip-to-chip due to voltage mismatch. This auto-direction translator can be conveniently used to bridge the gap without the need of direction control from the host. Each channel can be mixed and matched with different output types (open-drain or push-pull) and mixed data flows (transmit or receive) without intervention from the host. This 4-bit noninverting translator uses two separate configurable power-supply rails. The A and B ports are designed to track  $V_{CCA}$  and  $V_{CCB}$ respectively. The V<sub>CCB</sub> pin accepts any supply voltage from 2.3 V to 5.5 V while the  $V_{\text{CCA}}$  pin accepts any supply voltage from 1.65 V to 3.6 V such that  $V_{\text{CCA}}$ is less than or equal to V<sub>CCB</sub>. This tracking allows for low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state.

The TXS0104E-Q1 device is designed so that the OE input circuit is supplied by V<sub>CCA</sub>.

To be in the high-impedance state during power up or power down, the OE pin must be tied to the GND pin through a pull down resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

**Package Information** 

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>
TXS0104E-Q1	PW (TSSOP, 14)	5 mm × 6.4 mm
	BQA (WQFN, 14)	3 mm × 2.5 mm
	RUT (UQFN, 12)	2 mm × 1.7 mm

- For all available packages, see the orderable addendum at the end of the data sheet.
- The package size (length × width) is a nominal value and (2)includes pins, where applicable.



# **Table of Contents**

1 Features1	7 Detailed Description	16
2 Applications1	7.1 Overview	
3 Description1	7.2 Functional Block Diagram	
4 Pin Configuration and Functions3	7.3 Feature Description	
5 Specifications5	7.4 Device Functional Modes	17
5.1 Absolute Maximum Ratings5	8 Application and Implementation	18
5.2 ESD Ratings5	8.1 Application Information	. 18
5.3 Recommended Operating Conditions5	8.2 Typical Application	18
5.4 Thermal Information6	8.3 Power Supply Recommendations	
5.5 Electrical Characteristics6	8.4 Layout	20
5.6 Timing Requirements—V <sub>CCA</sub> = 1.8 V ± 0.15 V 7	9 Device and Documentation Support	
5.7 Timing Requirements—V <sub>CCA</sub> = 2.5 V ± 0.2 V	9.1 Documentation Support	21
5.8 Timing Requirements— $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$	9.2 Receiving Notification of Documentation Updates	21
5.9 Switching Characteristics—V <sub>CCA</sub> = 1.8 V ± 0.15 V 8	9.3 Support Resources	21
5.10 Switching Characteristics—V <sub>CCA</sub> = 2.5 V ± 0.2 V 10	9.4 Trademarks	21
5.11 Switching Characteristics—V <sub>CCA</sub> = 3.3 V ± 0.3 V 12	10 Electrostatic Discharge Caution	. 21
5.12 Typical Characteristics	11 Glossary	. 21
6 Parameter Measurement Information14	12 Revision History	
6.1 Load Circuits14	13 Mechanical, Packaging, and Orderable	
6.2 Voltage Waveforms15	Information	22



# **4 Pin Configuration and Functions**

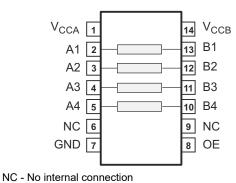
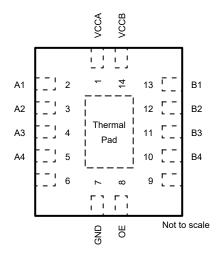


Figure 4-1. PW Package, 14-Pin TSSOP (Top View)



NC - No internal connection

Figure 4-2. BQA Package, 14-Pin WQFN (Top View)

**Table 4-1. Pin Functions** 

PIN		TYPE <sup>(1)</sup>	DESCRIPTION	
NAME	NO.	ITPE	DESCRIPTION	
A1	2	I/O	Input-output 1 for the A port. This pin is referenced to V <sub>CCA</sub> .	
A2	3	I/O	Input-output 2 for the A port. This pin is referenced to V <sub>CCA</sub> .	
A3	4	I/O	Input-output 3 for the A port. This pin is referenced to V <sub>CCA</sub> .	
A4	5	I/O	Input-output 4 for the A port. This pin is referenced to V <sub>CCA</sub> .	
B1	13	I/O	Input-output 1 for the B port. This pin is referenced to V <sub>CCB</sub> .	
B2	12	I/O	Input-output 2 for the B port. This pin is referenced to V <sub>CCB</sub> .	
В3	11	I/O	Input-output 3 for the B port. This pin is referenced to V <sub>CCB</sub> .	
B4	10	I/O	Input-output 4 for the B port. This pin is referenced to V <sub>CCB</sub> .	
GND	7	_	Ground	
NC	6		No connection	
INC	9	_	No connection	
OE	8	I	Tri-state output-mode enable. Pull the OE pin low to place all outputs in tri-state mode. This pin is referenced to V <sub>CCA</sub> .	
V <sub>CCA</sub>	1	I	A-port supply voltage. 1.65 V $\leq$ V <sub>CCA</sub> $\leq$ 3.6 V and V <sub>CCA</sub> $\leq$ V <sub>CCB</sub> .	
V <sub>CCB</sub>	14	I	B-port supply voltage. 2.3 V ≤ V <sub>CCB</sub> ≤ 5.5 V.	

(1) I = input, O = output



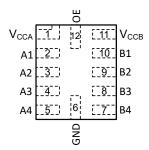


Figure 4-3. RUT Package, 12-Pin UQFN (Transparent Top View)

Table 4-2. Pin Functions: RUT

F	PIN	TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.	ITPE	DESCRIPTION
A1	2	I/O	Input/output A1. Referenced to V <sub>CCA</sub> .
A2	3	I/O	Input/output A2. Referenced to V <sub>CCA</sub> .
A3	4	I/O	Input/output A3. Referenced to V <sub>CCA</sub> .
A4	5	I/O	Input/output A4. Referenced to V <sub>CCA</sub> .
B1	10	I/O	Input/output B1. Referenced to V <sub>CCB</sub> .
B2	9	I/O	Input/output B2. Referenced to V <sub>CCB</sub> .
B3	8	I/O	Input/output B3. Referenced to V <sub>CCB</sub> .
B4	7	I/O	Input/output B4. Referenced to V <sub>CCB</sub> .
GND	6	_	Ground
OE	12	I	3-state output-mode enable. Pull OE low to place all outputs in 3-state mode. Referenced to $V_{\text{CCA}}$ .
V <sub>CCA</sub>	1	_	A-port supply voltage. 1.65 V $\leq$ V <sub>CCA</sub> $\leq$ 3.6 V and V <sub>CCA</sub> $\leq$ V <sub>CCB</sub> .
V <sub>CCB</sub>	11	_	A-port supply voltage. 1.65 V $\leq$ V <sub>CCA</sub> $\leq$ 3.6 V and V <sub>CCA</sub> $\leq$ V <sub>CCB</sub> .

(1) I = input, O = output

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# 5 Specifications

## 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
Supply voltage  Input-output pin voltage, V <sub>IO</sub> (2)	V <sub>CCA</sub>		-0.5	4.6	V
	V <sub>CCB</sub>		-0.5	6.5	\ \ \
Input-output pin voltage, V <sub>IO</sub> <sup>(2)</sup>	A1, A2, A3, A4	A port	-0.5	4.6	V
	B1, B2, B3, B4	B port	-0.5	6.5	
	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	A port	-0.5	4.6	V
Output valtage V		B port	-0.5	6.5	\ \ \
Output voltage, V <sub>O</sub>	Voltage range applied to any output in the high or low state <sup>(2) (3)</sup>	A port	-0.5	V <sub>CCA</sub> + 0.5	V
		B port	-0.5	V <sub>CCB</sub> + 0.5	
Input clamp current, I <sub>IK</sub>		V <sub>I</sub> < 0		-50	mA
Output clamp current, I <sub>OK</sub>		V <sub>O</sub> < 0		-50	mA
Continuous output current, I <sub>O</sub>				±50	mA
Continuous current through each V <sub>CCA</sub> , V <sub>CCB</sub> , or GND				±100	mA
Storage temperature range, T <sub>stg</sub>				150	°C

<sup>(1)</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# 5.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub> Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±2500	V	
	Liectiostatic discharge	Charged-device model (CDM), per AEC Q100-011	±1500	V

<sup>(1)</sup> AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

## 5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage <sup>(1)</sup>				1.65	3.6	V
V <sub>CCB</sub>	Supply voltage <sup>(1)</sup>				2.3	5.5	V
V	High-level input voltage	A-port I/Os	1.65 to 1.95 V	2.3 to 5.5 V	V <sub>CCA</sub> - 0.2	$V_{CCA}$	
$V_{IH(Ax)}$	nigii-level iliput voltage	A-port i/Os	2.3 to 3.6 V	2.3 to 5.5 v	V <sub>CCA</sub> - 0.4	V <sub>CCA</sub>	V
V <sub>IH(Bx)</sub>	High-level input voltage	B-port I/Os	1.65 to 3.6 V	2.3 to 5.5 V	V <sub>CCB</sub> - 0.4	V <sub>CCB</sub>	V
V <sub>IH(OE)</sub>	High-level input voltage	OE input	1.05 to 5.0 v	2.3 to 5.5 v	V <sub>CCA</sub> × 0.65	5.5	
V <sub>IL(Ax)</sub>	Low-level input voltage	A-port I/Os			0	0.15	
V <sub>IL(Bx)</sub>	Low-level input voltage	B-port I/Os	1.65 to 3.6 V	2.3 to 5.5 V	0	0.15	V
V <sub>IL(OE)</sub>	Low-level input voltage	OE input			0	V <sub>CCA</sub> × 0.35	
$\Delta t/\Delta v_{(Ax)}$	Input transition rise or fall rate	A-port I/Os, push-pull driving				10	
$\Delta t/\Delta v_{(Bx)}$	Input transition rise or fall rate	B-port I/Os, push-pull driving	1.65 to 3.6 V	2.3 to 5.5 V		10	ns/V
$\Delta t/\Delta v_{(OE)}$	Input transition rise or fall rate	OE input				10	
T <sub>A</sub>	Operating free-air temperature				-40	125	°C

<sup>(1)</sup>  $V_{CCA}$  must be less than or equal to  $V_{CCB}$ , and  $V_{CCA}$  must not exceed 3.6 V.

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<sup>(2)</sup> The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> The value of V<sub>CCA</sub> and V<sub>CCB</sub> are provided in the recommended operating conditions table.



#### **5.4 Thermal Information**

over operating free-air temperature range (unless otherwise noted) (1)

	THERMAL METRIC(1)	PW (TSSOP)	BQA (WQFN)	RUT (UQFN)	UNIT
		14 PINS	14 PINS	12 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	115.2	73.5	150.4	°C/W
R <sub>0JC(top)</sub>	Junction-to-case (top) thermal resistance	46.2	76.9	68.6	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	70.9	43.0	76.3	°C/W
ΨЈТ	Junction-to-top characterization parameter	3.4	4.7	2.4	°C/W
ΨЈВ	Junction-to-board characterization parameter	70.2	42.9	76.2	°C/W
R <sub>0JC(bot)</sub>	Junction-to-case (bottom) thermal resistance	_	19.6	_	°C/W

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

## 5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (1)

	PARAMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	TYP	MAX	UNIT
V <sub>OH(Ax)</sub>	High-level output voltage, A port	$I_{OH} = -20 \mu A,$ $V_{I(Bx)} \ge V_{CCB} - 0.4 V$	1.65 to 3.6 V	2.3 to 5.5 V	V <sub>CCA</sub> × 0.75			V
V <sub>OL(Ax)</sub>	Low-level output voltage, A port	I <sub>OL</sub> = 1 mA, V <sub>I(Bx)</sub> ≤ 0.15 V	1.65 to 3.6 V	2.3 to 5.5 V			0.4	V
V <sub>OH(Bx)</sub>	High-level output voltage, B port	$I_{OH} = -20 \mu A,$ $V_{I(Ax)} \ge V_{CCA} - 0.2 V$	1.65 to 3.6 V	2.3 to 5.5 V	V <sub>CCB</sub> × 0.75			V
V <sub>OL(Bx)</sub>	Low-level output voltage, B port	I <sub>OL</sub> = 1 mA, V <sub>I(Ax)</sub> ≤ 0.15 V	1.65 to 3.6 V	2.3 to 5.5 V			0.4	V
		V <sub>I</sub> = V <sub>CCI</sub> or GND					±2	
I <sub>I(OE)</sub>	Input current, OE	V <sub>I</sub> = V <sub>CCI</sub> or GND, T <sub>A</sub> = 25°C	1.65 to 3.6 V	2.3 to 5.5 V			±1	μΑ
	O# -1-111 A	OE = V <sub>IL</sub>					±3	
l <sub>OZ</sub>	Off-state output current, A or B port		1.65 to 3.6 V	2.3 to 5.5 V			±1	μΑ
			1.65 to V <sub>CCB</sub>	2.3 to 5.5 V			4	
I <sub>CCA</sub>	Supply current, A port	upply current, A port $\begin{vmatrix} V_1 = V_O = \text{Open}, \\ I_O = 0 \end{vmatrix}$	3.6 V	0			2.2	μA
			0	5.5 V			-1	
			1.65 to V <sub>CCB</sub>	2.3 to 5.5 V			21	
I <sub>CCB</sub>	Supply current, B port	$V_I = V_O = Open,$ $I_O = 0$	3.6 V	0			-1	μΑ
		.0 0	0	5.5 V			5	
I <sub>CCA</sub> +I <sub>CCB</sub>	Supply current, A port plus B port supply current	$V_I = V_O = Open,$ $I_O = 0$	1.65 V to V <sub>CCB</sub>	2.3 to 5.5 V			25	μΑ
	Innuit conscitones OF		221/	221/			4	r
C <sub>I(OE)</sub>	Input capacitance, OE	T <sub>A</sub> = 25°C	3.3 V	3.3 V		2.5		pF
<u> </u>	Input-output capacitance, A						6.5	
C <sub>IO(Ax)</sub>	port	T <sub>A</sub> = 25°C	3.3 V	3.3 V		5		
	Input-output capacitance, B						16.5	pF
C <sub>IO(Bx)</sub>	port	T <sub>A</sub> = 25°C				12		

(1)  $V_{CCA}$  must be less than or equal to  $V_{CCB}$ , and  $V_{CCA}$  must not exceed 3.6 V.

Product Folder Links: TXS0104E-Q1



# 5.6 Timing Requirements— $V_{CCA}$ = 1.8 V ± 0.15 V

over recommended operating free-air temperature range (unless otherwise noted)

				MIN MAX	UNIT
Data rate			V <sub>CCB</sub> = 2.5 V ± 0.2 V	18	3
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	21	
	Data rato		V <sub>CCB</sub> = 5 V ± 0.5 V	23	Mbps
	Data rate		V <sub>CCB</sub> = 2.5 V ± 0.2 V	2	iviops
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	2	
			V <sub>CCB</sub> = 5 V ± 0.5 V	2	
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	55	
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	47	
	Pulse duration, data		V <sub>CCB</sub> = 5 V ± 0.5 V	43	] no
t <sub>w</sub>	inputs See Figure 6-4		V <sub>CCB</sub> = 2.5 V ± 0.2 V	500	ns
	-	Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	500	
			V <sub>CCB</sub> = 5 V ± 0.5 V	500	

# 5.7 Timing Requirements— $V_{CCA}$ = 2.5 V ± 0.2 V

over recommended operating free-air temperature range (unless otherwise noted)

	<u> </u>	<u> </u>		MIN MAX	UNIT
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	20	
Dat		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	22	
	Data rate		V <sub>CCB</sub> = 5 V ± 0.5 V	24	Mbps
	Data Tate		V <sub>CCB</sub> = 2.5 V ± 0.2 V	2	Minhs
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	2	
			$V_{CCB} = 5 V \pm 0.5 V$	2	
		Push-pull driving	V <sub>CCB</sub> = 2.5 V ± 0.2 V	50	
			V <sub>CCB</sub> = 3.3 V ± 0.3 V	45	
	Pulse duration, data		V <sub>CCB</sub> = 5 V ± 0.5 V	41	ns
t <sub>w</sub>	See Figure 6-4	Poputs See Figure 6-4 Open-drain driving	V <sub>CCB</sub> = 2.5 V ± 0.2 V	500	115
			V <sub>CCB</sub> = 3.3 V ± 0.3 V	500	
			V <sub>CCB</sub> = 5 V ± 0.5 V	500	

# 5.8 Timing Requirements— $V_{CCA}$ = 3.3 V ± 0.3 V

over recommended operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
Data rate		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V		22	
	Data rata	Push-pull driving	V <sub>CCB</sub> = 5 V ± 0.5 V		24	Mbps
	Data rate	Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V		2	IVIDPS
			V <sub>CCB</sub> = 5 V ± 0.5 V		2	
		Duch pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	45		
	Pulse duration, Data	Pulse duration, Data inputs See Figure 6-4  Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V	41		no
t <sub>w</sub>	'		V <sub>CCB</sub> = 3.3 V ± 0.3 V	500		ns
	•		$V_{CCB} = 5 V \pm 0.5 V$	500		

Product Folder Links: TXS0104E-Q1



# 5.9 Switching Characteristics— $V_{CCA}$ = 1.8 V ± 0.15 V

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST	CONDITIONS	MIN MAX	UNIT	
		V <sub>CCB</sub> = 2.5 V ± 0.2 V		6		
	Propagation delay time (high to low), from A (input) to B (output) See Figure 6-5	Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	5.8		
			$V_{CCB} = 5 V \pm 0.5 V$	5.8		
PHL(A-B)			V <sub>CCB</sub> = 2.5 V ± 0.2 V	8.8		
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	9.6		
			$V_{CCB} = 5 V \pm 0.5 V$	10		
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	4.4	ns	
		Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	4.5		
	Propagation delay time (high to low), from		$V_{CCB} = 5 V \pm 0.5 V$	4.7		
t <sub>PHL(B-A)</sub>	B (input) to A (output) See Figure 6-5		V <sub>CCB</sub> = 2.5 V ± 0.2 V	5.3		
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	4.4		
			V <sub>CCB</sub> = 5 V ± 0.5 V	4		
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	7.7		
t <sub>PLH(A-B)</sub>		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	6.8		
	Propagation delay time (low to high), from		$V_{CCB} = 5 V \pm 0.5 V$	7		
	A (input) to B (output) See Figure 6-5		V <sub>CCB</sub> = 2.5 V ± 0.2 V	50		
	Coo Figure 0 0	Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	26		
			$V_{CCB} = 5 V \pm 0.5 V$	33		
	Propagation delay time (low to high), from <i>B</i> (input) to <i>A</i> (output) See Figure 6-5		V <sub>CCB</sub> = 2.5 V ± 0.2 V	5.3	ns	
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	4.5		
_			$V_{CCB} = 5 V \pm 0.5 V$	0.5		
t <sub>PLH(B-A)</sub>			V <sub>CCB</sub> = 2.5 V ± 0.2 V	36		
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	16		
			V <sub>CCB</sub> = 5 V ± 0.5 V	20		
		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$				
en(OE-A)	Enable time, from <i>OE</i> (input) to <i>A</i> or <i>B</i> (output)	V <sub>CCB</sub> = 3.3 V ± 0.3 V		200	ns	
t <sub>en(OE-B)</sub>	or B (output)	V <sub>CCB</sub> = 5 V ± 0.5 V		200		
		V <sub>CCB</sub> = 2.5 V ± 0.2 V		200		
dis(OE-A)	Disable time, from <i>OE</i> (input) to <i>A</i> or <i>B</i> (output)	V <sub>CCB</sub> = 3.3 V ± 0.3 V		200	ns	
t <sub>dis(OE-B)</sub>	or B (output)	V <sub>CCB</sub> = 5 V ± 0.5 V		200		
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	9.5		
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	9.3		
			V <sub>CCB</sub> = 5 V ± 0.5 V	15		
t <sub>r(Ax)</sub>	Rise time, A port		V <sub>CCB</sub> = 2.5 V ± 0.2 V	38 199	ns	
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	30 150		
		_	V <sub>CCB</sub> = 5 V ± 0.5 V	22 109		
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	10.8		
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	9.1		
			$V_{CCB} = 5 V \pm 0.5 V$	7.6	ns	
$t_{r(Bx)}$	Rise time, B port		V <sub>CCB</sub> = 2.5 V ± 0.2 V	34 186		
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	23 112		
			$V_{CCB} = 5 V \pm 0.5 V$	10 58		

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# 5.9 Switching Characteristics— $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST	CONDITIONS	MIN MAX	UNIT	
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	5.9		
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	6		
	Fall time, A port		V <sub>CCB</sub> = 5 V ± 0.5 V	13.3		
t <sub>f(Ax)</sub>	Fall tille, A port		V <sub>CCB</sub> = 2.5 V ± 0.2 V	6.9		
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	6.4		
			V <sub>CCB</sub> = 5 V ± 0.5 V	6.1	20	
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	7.6	ns	
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	7.5		
	Fall time, B port		V <sub>CCB</sub> = 5 V ± 0.5 V	8.8		
t <sub>f(Bx)</sub>			V <sub>CCB</sub> = 2.5 V ± 0.2 V	13.8		
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	16.2		
			V <sub>CCB</sub> = 5 V ± 0.5 V	16.2		
		V <sub>CCB</sub> = 2.5 V ± 0.2 V		1		
t <sub>sk</sub>	Channel-to-channel skew	V <sub>CCB</sub> = 3.3 V ± 0.3 V		1	ns	
		V <sub>CCB</sub> = 5 V ± 0.5 V		1		
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	18		
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	21		
	Mariana data nata		V <sub>CCB</sub> = 5 V ± 0.5 V	23	Missa	
	Maximum data rate		V <sub>CCB</sub> = 2.5 V ± 0.2 V	2	Mbps	
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	2		
			$V_{CCB} = 5 V \pm 0.5 V$	2	ı	



# 5.10 Switching Characteristics— $V_{CCA}$ = 2.5 V ± 0.2 V

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN MAX	UNIT
			$V_{CCB} = 2.5 V \pm 0.2 V$	3.2	2
	Propagation delay time (high to low), from	Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	3.3	3
t <sub>PHL(A-B)</sub>			V <sub>CCB</sub> = 5 V ± 0.5 V	3.4	1
	A (input) to B (output) See Figure 6-5		V <sub>CCB</sub> = 2.5 V ± 0.2 V	6.3	3
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	6	5
			V <sub>CCB</sub> = 5 V ± 0.5 V	5.8	
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	3	ns
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	3.6	5
	Propagation delay time (high to low), from		V <sub>CCB</sub> = 5 V ± 0.5 V	4.3	3
t <sub>PHL(B-A)</sub>	B (input) to A (output) See Figure 6-5		V <sub>CCB</sub> = 2.5 V ± 0.2 V	4.7	,
	3	Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	4.2	2
			V <sub>CCB</sub> = 5 V ± 0.5 V		
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	3.5	5
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	4.1	1
	Propagation delay time (low to high), from		$V_{CCB} = 5 V \pm 0.5 V$	4.4	i
PLH(A-B)	A (input) to B (output) See Figure 6-5		V <sub>CCB</sub> = 2.5 V ± 0.2 V	3.5	-
	Occ Figure 0-0	Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	4.1	-
		3	V <sub>CCB</sub> = 5 V ± 0.5 V	4.4	-
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	2.5	– ns
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	1.6	-
			$V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$	0.7	-
			$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	2.5	-
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	1.6	-
		Open-drain driving	$V_{CCB} = 5.5 \text{ V} \pm 0.5 \text{ V}$		-
		V <sub>CCB</sub> = 2.5 V ± 0.2 V		200	
en(OE-A)	Enable time, from <i>OE</i> (input) to <i>A</i> or <i>B</i>	$V_{CCB} = 2.3 \text{ V} \pm 0.2 \text{ V}$ $V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		200	_
en(OE-B)	(output)	$V_{CCB} = 5.3 \text{ V} \pm 0.5 \text{ V}$ $V_{CCB} = 5 \text{ V} \pm 0.5 \text{ V}$		200	-
dis(OE-A)	Disable time, from <i>OE</i> (input) to <i>A</i> or <i>B</i>	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		200	-
dis(OE-B)	(output)	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		200	-
		$V_{CCB} = 5 V \pm 0.5 V$	V - 0.5.V : 0.0.V	200	+
		December and definition	$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	7.4	-
		Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	6.6	-
r(Ax)	Rise time, A port		V <sub>CCB</sub> = 5 V ± 0.5 V	5.6	ns
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	34 180	-
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	28 150	-
			V <sub>CCB</sub> = 5 V ± 0.5 V	24 105	
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	8.3	-
		Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	7.2	-
r(Bx)	Rise time, B port		$V_{CCB} = 5 V \pm 0.5 V$	6.1	ns
(5/1)	, ,		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$	35 170	
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	24 120	)
			$V_{CCB} = 5 V \pm 0.5 V$	12 64	+
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	5.7	
		Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	5.5	5
	Fall time. A port		V <sub>CCB</sub> = 5 V ± 0.5 V	5.3	
f(Ax)	Fall time, A port		V <sub>CCB</sub> = 2.5 V ± 0.2 V		ns
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V		7
			V <sub>CCB</sub> = 5 V ± 0.5 V	5.8	3

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# 5.10 Switching Characteristics— $V_{CCA}$ = 2.5 V ± 0.2 V (continued)

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN MAX	UNIT
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	7.8	
		Push-pull driving	$V_{CCB} = 3.3 V \pm 0.3 V$	6.7	
<b>.</b>	Fall time, B port		$V_{CCB} = 5 V \pm 0.5 V$	6.6	no
t <sub>f(Bx)</sub>	ған шпе, <b>Б</b> роп		V <sub>CCB</sub> = 2.5 V ± 0.2 V	8.8	ns
		Open-drain driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	9.4	
			V <sub>CCB</sub> = 5 V ± 0.5 V	10.4	
		V <sub>CCB</sub> = 2.5 V ± 0.2 V		1	
t <sub>sk</sub>	Channel-to-channel skew	V <sub>CCB</sub> = 3.3 V ± 0.3 V		1	ns
		V <sub>CCB</sub> = 5 V ± 0.5 V		1	
			V <sub>CCB</sub> = 2.5 V ± 0.2 V	20	
		Push-pull driving	$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$	22	
	Maximum data rate		V <sub>CCB</sub> = 5 V ± 0.5 V	24	Mhna
	waximum data rate		V <sub>CCB</sub> = 2.5 V ± 0.2 V	2	Mbps
		Open-drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	2	
			V <sub>CCB</sub> = 5 V ± 0.5 V	2	



# 5.11 Switching Characteristics— $V_{CCA}$ = 3.3 V ± 0.3 V

over recommended operating free-air temperature range (unless otherwise noted)

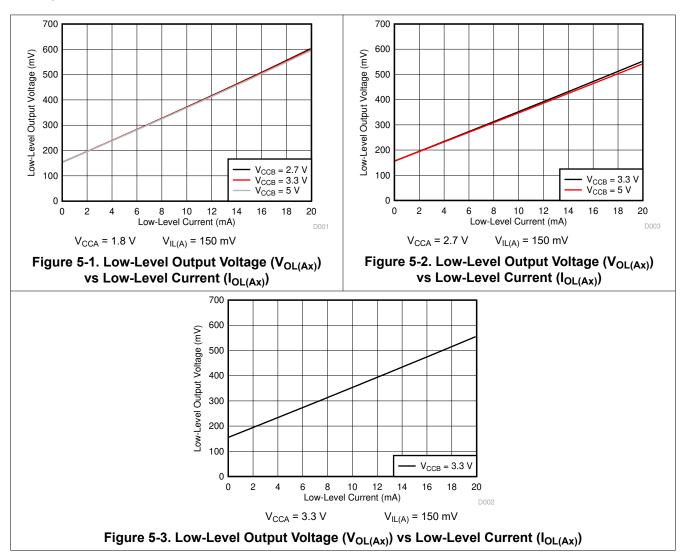
	PARAMETER	TEST	MIN	UNIT				
		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$			2.4			
	Propagation delay time (high to low), from <i>A</i> (input) to <i>B</i> (output) See Figure 6-5	Push-pull driving	V <sub>CCB</sub> = 5 V ± 0.5 V		3.1			
PHL(A-B)		0 desir dei in -	V <sub>CCB</sub> = 3.3 V ± 0.3 V		4.2	ı		
	_	Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V		4.6			
		D 1 11111	V <sub>CCB</sub> = 3.3 V ± 0.3 V		2.5	ns		
	Propagation delay time (high to low),	Push-pull driving	V <sub>CCB</sub> = 5 V ± 0.5 V		3.3			
t <sub>PHL(B-A)</sub>	from B (input) to A (output) See Figure 6-5	0 desir dei in -	V <sub>CCB</sub> = 3.3 V ± 0.3 V		124			
	_	Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V		97			
		Donale and I daining	V <sub>CCB</sub> = 3.3 V ± 0.3 V		4.2			
	Propagation delay time (low to high),	Push-pull driving	V <sub>CCB</sub> = 5 V ± 0.5 V		4.4			
PLH(A-B)	from A (input) to B (output) See Figure 6-5	0 desir dei in	V <sub>CCB</sub> = 3.3 V ± 0.3 V		4.2			
		Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V		4.4			
		D 1 11111	V <sub>CCB</sub> = 3.3 V ± 0.3 V		2.5	ns		
	Propagation delay time (low to high),	Push-pull driving	V <sub>CCB</sub> = 5 V ± 0.5 V		2.6			
PLH(B-A)	from B (input) to A (output) See Figure 6-5		V <sub>CCB</sub> = 3.3 V ± 0.3 V		2.5			
	Sec. Igaile 6.6	Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V		3.3			
en(OE-A) Enable time, from OE (input) to A or B		V <sub>CCB</sub> = 3.3 V ± 0.3 V			200			
en(OE-A)	(output)	V <sub>CCB</sub> = 5 V ± 0.5 V		200	ns			
dis(OE-A)	Disable time,from <i>OE</i> (input) to <i>A</i> or <i>B</i>	V <sub>CCB</sub> = 3.3 V ± 0.3 V			200			
t <sub>dis(OE-B)</sub> (output		V <sub>CCB</sub> = 5 V ± 0.5 V			200	ns		
	Rise time, A port		V <sub>CCB</sub> = 3.3 V ± 0.3 V		5.6			
		Push-pull driving	V <sub>CCB</sub> = 5 V ± 0.5 V		5			
r(Ax)		On an drain driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V	25	140	ns		
		Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V	19	102			
		Push-pull driving	V <sub>CCB</sub> = 3.3 V ± 0.3 V		6.4			
			V <sub>CCB</sub> = 5 V ± 0.5 V		7.4			
r(Bx)	Rise time, B port		V <sub>CCB</sub> = 3.3 V ± 0.3 V	26	130	ns		
		Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V	14	75			
			V <sub>CCB</sub> = 3.3 V ± 0.3 V		5.4			
		Push-pull driving	V <sub>CCB</sub> = 5 V ± 0.5 V		5			
(Ax)	Fall time, A port		V <sub>CCB</sub> = 3.3 V ± 0.3 V		6.1	ns		
		Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V		5.7			
			V <sub>CCB</sub> = 3.3 V ± 0.3 V		7.4			
		Push-pull driving	V <sub>CCB</sub> = 5 V ± 0.5 V		7.6			
(Bx)	Fall time, B port		V <sub>CCB</sub> = 3.3 V ± 0.3 V		7.6	ns		
		Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V		8.3			
		V <sub>CCB</sub> = 3.3 V ± 0.3 V			1			
k	Channel-to-channel skew	V <sub>CCB</sub> = 5 V ± 0.5 V			1	ns		
			V <sub>CCB</sub> = 3.3 V ± 0.3 V	22				
		Push-pull driving	$V_{CCB} = 5 V \pm 0.5 V$	24				
	Maximum data rate		V <sub>CCB</sub> = 3.3 V ± 0.3 V	2		Mbps		
		Open-drain driving	V <sub>CCB</sub> = 5 V ± 0.5 V	2				

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# **5.12 Typical Characteristics**



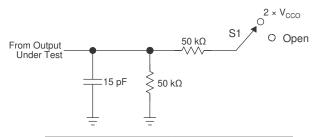
# **6 Parameter Measurement Information**

#### **6.1 Load Circuits**



Figure 6-1. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Propagation Delay, Output Rise-Time and Fall-Time Measurement Using a Push-Pull Driver

Figure 6-2. Data Rate, Pulse Duration, Measurement Using an Open-Drain Driver



TEST	S1		
t <sub>PZL</sub> / t <sub>PLZ</sub> (t <sub>dis</sub> )	2 × V <sub>CCO</sub>		
t <sub>PHZ</sub> / t <sub>PZH</sub> (t <sub>en</sub> )	Open		

Figure 6-3. Load Circuit for Enable-Time and Disable-Time Measurement

- 1.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- 2.  $\,\,t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}.$
- 3.  $V_{\text{CCI}}$  is the  $V_{\text{CC}}$  associated with the input port.
- 4.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

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## 6.2 Voltage Waveforms

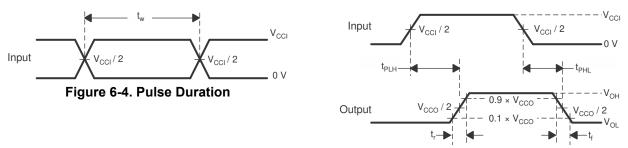
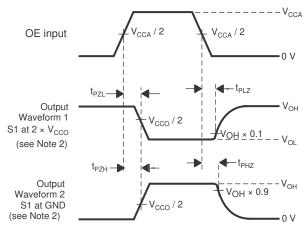


Figure 6-5. Propagation Delay Times



- 1. C<sub>L</sub> includes probe and jig capacitance.
- 2. Waveform 1 in Figure 6-6 is for an output with internal such that the output is high, except when OE is high (see Figure 6-3). Waveform 2 in Figure 6-6 is for an output with conditions such that the output is low, except when OE is high.
- 3. All input pulses are supplied by generators having the following characteristics: PRR≤ 10 MHz, Z<sub>O</sub> = 50 Ω, dv/dt ≥ 1 V/ns.
- 4. The outputs are measured one at a time, with one transition per measurement.
- 5.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- 6.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- 7.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- 8.  $V_{CCI}$  is the  $V_{CC}$  associated with the input port.
- 9.  $V_{\text{CCO}}$  is the  $V_{\text{CC}}$  associated with the output port.

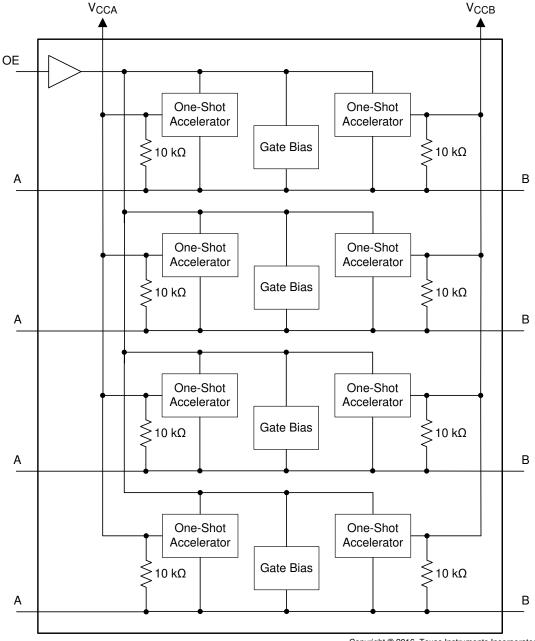
Figure 6-6. Enable and Disable Times

# 7 Detailed Description

#### 7.1 Overview

The TXS0104E-Q1 device is a directionless voltage-level translator specifically designed for translating logic voltage levels. The A port is able to accept I/O voltages ranging from 1.65 V to 3.6 V, while the B port can accept I/O voltages from 2.3 V to 5.5 V. The device is a pass gate architecture with edge rate accelerators (one shots) to improve the overall data rate. 10-k $\Omega$  pullup resistors, commonly used in open drain applications, have been conveniently integrated so that an external resistor is not needed. While this device is designed for open drain applications, the device can also translate push-pull CMOS logic outputs.

# 7.2 Functional Block Diagram



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#### 7.3 Feature Description

#### 7.3.1 Architecture

The TXS0104E-Q1 architecture (see Figure 7-1) does not require a direction-control signal in order to control the direction of data flow from A to B or from B to A.

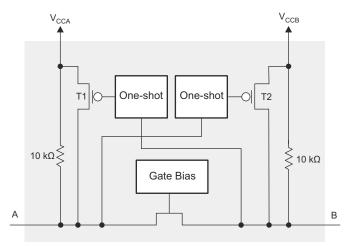


Figure 7-1. Architecture of a TXS01xx Cell

Each A-port I/O has an internal  $10-k\Omega$  pullup resistor to  $V_{CCA}$ , and each B-port I/O has an internal  $10-k\Omega$  pullup resistor to  $V_{CCB}$ . The output one-shots detect rising edges on the A or B ports. During a rising edge, the one-shot turns on the PMOS transistors (T1, T2) for a short duration which speeds up the low-to-high transition.

#### 7.3.2 Input Driver Requirements

The fall time ( $t_{fA}$ ,  $t_{fB}$ ) of a signal depends on the output impedance of the external device driving the data I/Os of the TXS0104E-Q1 device. Similarly, the  $t_{PHL}$  and maximum data rates also depend on the output impedance of the external driver. The values for  $t_{fA}$ ,  $t_{fB}$ ,  $t_{PHL}$ , and maximum data rates in the data sheet assume that the output impedance of the external driver is less than 50  $\Omega$ .

#### 7.3.3 Power Up

During operation, ensure that  $V_{CCA} \le V_{CCB}$  at all times. During power-up sequencing,  $V_{CCA} \ge V_{CCB}$  does not damage the device, so any power supply can be ramped up first.

#### 7.3.4 Enable and Disable

The TXS0104E-Q1 device has an OE input that disables the device by setting OE low, which places all I/Os in the high-impedance state. The disable time ( $t_{dis}$ ) indicates the delay between the time when the OE pin goes low and when the outputs actually enter the high-impedance state. The enable time ( $t_{en}$ ) indicates the amount of time the user must allow for the one-shot circuitry to become operational after the OE pin is taken high.

#### 7.3.5 Pull Up and Pull Down Resistors on I/O Lines

Each A-port I/O has an internal  $10-k\Omega$  pullup resistor to  $V_{CCA}$ , and each B-port I/O has an internal  $10-k\Omega$  pullup resistor to  $V_{CCB}$ . If a smaller value of pullup resistor is required, an external resistor must be added from the I/O to  $V_{CCA}$  or  $V_{CCB}$  (in parallel with the internal  $10-k\Omega$  resistors).

#### 7.4 Device Functional Modes

The TXS0104E-Q1 device has two functional modes, enabled and disabled. To disable the device set the OE input low, which places all I/Os in a high impedance state. Setting the OE input high will enable the device.

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# 8 Application and Implementation

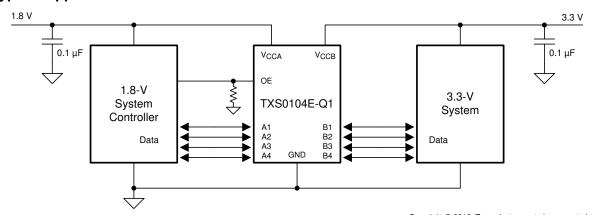
#### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

## 8.1 Application Information

The TXS0104E-Q1 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The TXS0104E-Q1 device is optimal for use in applications where an open-drain driver is connected to the data I/Os. The TXS0104E-Q1 device can also be used in applications where a push-pull driver is connected to the data I/Os, but the TXB0104-Q1 device might be a better option for such push-pull applications.

### 8.2 Typical Application



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Figure 8-1. Application Schematic

### 8.2.1 Design Requirements

For this design example, use the parameters listed in Table 8-1.

**Table 8-1. Design Parameters** 

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	1.65 to 3.6 V
Output voltage range	2.3 to 5.5 V

#### 8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
  - Use the supply voltage of the device that is driving the TXS0104E-Q1 device to determine the input voltage range. For a valid logic high the value must exceed the VIH of the input port. For a valid logic low the value must be less than the  $V_{II}$  of the input port.
- Output voltage range
  - Use the supply voltage of the device that the TXS0104E-Q1 device is driving to determine the output voltage range.
  - The TXS0104E-Q1 device has 10-kΩ internal pullup resistors. External pullup resistors can be added to reduce the total RC of a signal trace if necessary.

Product Folder Links: TXS0104E-Q1

An external pull down resistor decreases the output V<sub>OH</sub> and V<sub>OL</sub>. Use Equation 1 to calculate the V<sub>OH</sub> as a
result of an external pull down resistor.

$$V_{OH} = V_{CCx} \times R_{PD} / (R_{PD} + 10 \, k\Omega) \tag{1}$$

#### where

- $V_{CCx}$  is the supply voltage on either  $V_{CCA}$  or  $V_{CCB}$
- · R<sub>PD</sub> is the value of the external pull down resistor

### 8.2.3 Application Curve

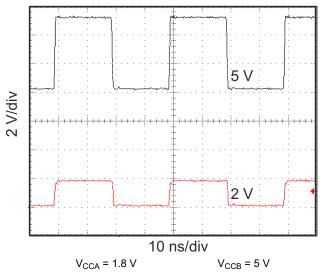


Figure 8-2. Level-Translation of a 2.5-MHz Signal

## 8.3 Power Supply Recommendations

The TXS0104E-Q1 device uses two separate configurable power-supply rails,  $V_{CCA}$  and  $V_{CCB}$ .  $V_{CCB}$  accepts any supply voltage from 2.3 V to 5.5 V and  $V_{CCA}$  accepts any supply voltage from 1.65 V to 3.6 V as long as Vs is less than or equal to  $V_{CCB}$ . The A port and B port are designed to track  $V_{CCA}$  and  $V_{CCB}$  respectively allowing for low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

The TXS0104E-Q1 device does not require power sequencing between  $V_{CCA}$  and  $V_{CCB}$  during power-up so the power-supply rails can be ramped in any order. A  $V_{CCA}$  value greater than or equal to  $V_{CCB}$  ( $V_{CCA} \ge V_{CCB}$ ) does not damage the device, but during operation,  $V_{CCA}$  must be less than or equal to  $V_{CCB}$  ( $V_{CCA} \le V_{CCB}$ ) at all times.

The output-enable (OE) input circuit is designed so that it is supplied by  $V_{CCA}$  and when the (OE) input is low, all outputs are placed in the high-impedance state. To enable the high-impedance state of the outputs during power up or power down, the OE input pin must be tied to GND through a pull down resistor and must not be enabled until  $V_{CCA}$  and  $V_{CCB}$  are fully ramped and stable. The minimum value of the pull down resistor to ground is determined by the current-sourcing capability of the driver.

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## 8.4 Layout

#### 8.4.1 Layout Guidelines

For reliability of the device, following common printed-circuit board layout guidelines is recommended.

- · Bypass capacitors should be used on power supplies.
- Short trace lengths should be used to avoid excessive loading.
- PCB signal trace-lengths must be kept short enough so that the round-trip delay of any reflection is less than the one shot duration, approximately 30 ns, ensuring that any reflection encounters low impedance at the source driver.
- Placing pads on the signal paths for loading capacitors or pullup resistors to help adjust rise and fall times of signals depending on the system requirements

#### 8.4.2 Layout Example

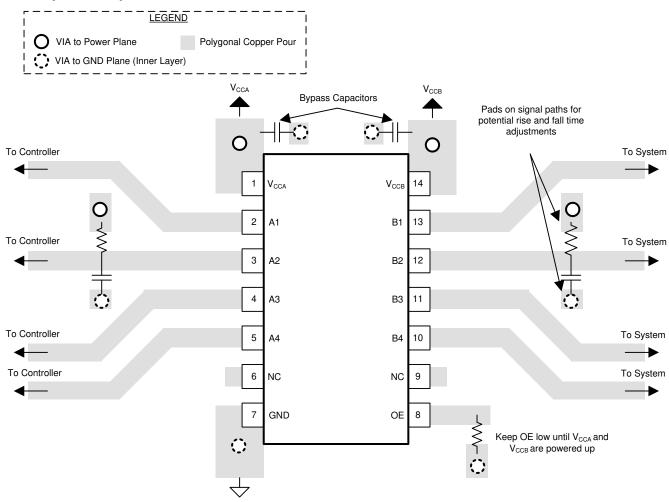


Figure 8-3. TXS0104E-Q1 Layout Example

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# 9 Device and Documentation Support

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

For related documentation, see the following:

Texas Instruments, Introduction to Logic application note

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

# 9.3 Support Resources

TI E2E<sup>™</sup> support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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#### 9.4 Trademarks

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## 10 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

# 11 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

## 12 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision E (October 2023) to Revision F (October 2024)	Page
Updated thermal values for new packages	6
Changes from Revision D (January 2017) to Revision E (October 2023)	Page
Added the RUT package information to the data sheet	1
Changes from Revision C (January 2017) to Revision D (June 2023)	Page
<ul> <li>Updated the numbering format for tables, figures, and cross-references throughout the</li> <li>Added the BQA package information to the data sheet.</li> </ul>	

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Ch	anges from Revision B (May 2014) to Revision C (January 2017)	Page
	Changed the type of the OE pin from output (O) to input (I) in the <i>Pin Functions</i> table	
	Moved T <sub>stg</sub> back to the <i>Absolute Maximum Ratings</i> table and changed the <i>Handling Ratings</i> table to <i>E Ratings</i>	
Ch	nanges from Revision A (April 2014) to Revision B (May 2014)	Page
	Changed device status from Product Preview to Production Data	1

# 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Product Folder Links: TXS0104E-Q1

www.ti.com 7-Nov-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
TXS0104EQPWRQ1	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	04EQ1
TXS0104EQPWRQ1.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	04EQ1
TXS0104EQPWRQ1.B	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	04EQ1
TXS0104EQRUTRQ1	Active	Production	UQFN (RUT)   12	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1RQ
TXS0104EQRUTRQ1.A	Active	Production	UQFN (RUT)   12	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1RQ
TXS0104EQWBQARQ1	Active	Production	WQFN (BQA)   14	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	YF04EQ
TXS0104EQWBQARQ1.A	Active	Production	WQFN (BQA)   14	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	YF04EQ

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF TXS0104E-Q1:

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 25-Jul-2025

## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TXS0104EQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TXS0104EQRUTRQ1	UQFN	RUT	12	3000	180.0	8.4	2.0	2.3	0.75	4.0	8.0	Q1
TXS0104EQWBQARQ1	WQFN	BQA	14	3000	180.0	12.4	2.8	3.3	1.1	4.0	12.0	Q1

www.ti.com 25-Jul-2025



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TXS0104EQPWRQ1	TSSOP	PW	14	2000	353.0	353.0	32.0
TXS0104EQRUTRQ1	UQFN	RUT	12	3000	210.0	185.0	35.0
TXS0104EQWBQARQ1	WQFN	BQA	14	3000	210.0	185.0	35.0

2.5 x 3, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.





NOTES: (continued)

- 4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
- 5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



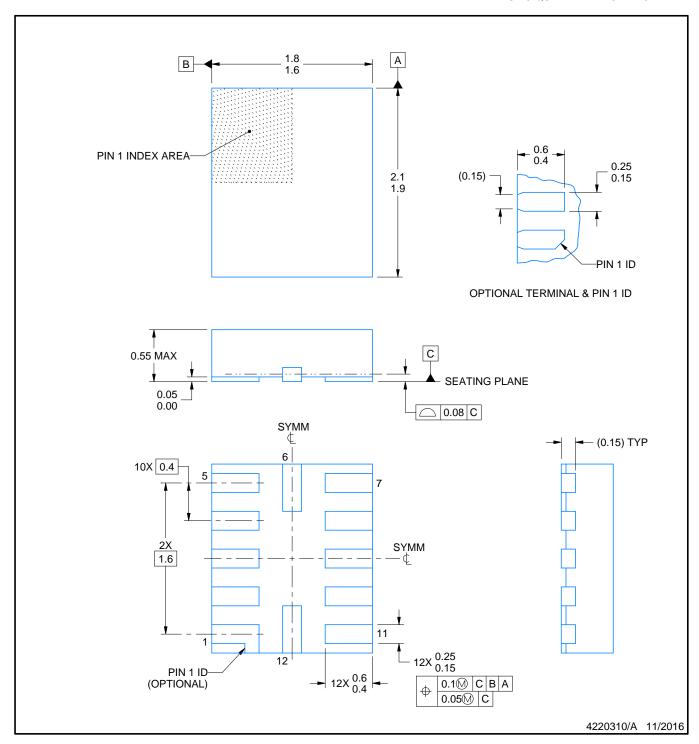


NOTES: (continued)

<sup>6.</sup> Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



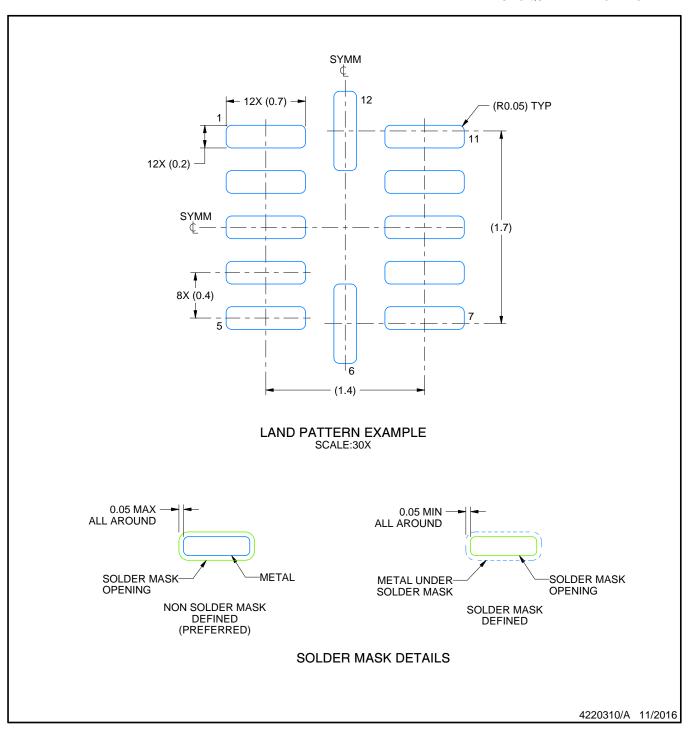




#### NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
   This drawing is subject to change without notice.

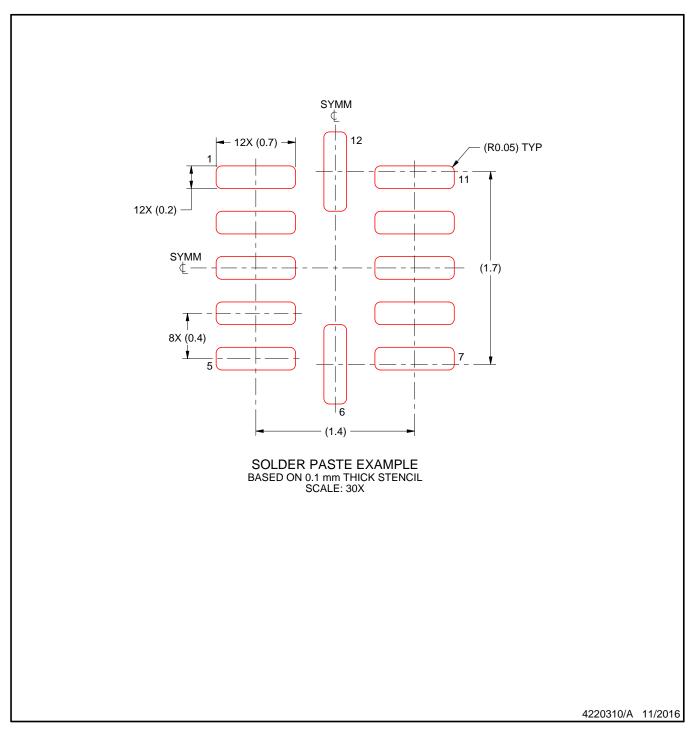




NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).





NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.





SMALL OUTLINE PACKAGE



#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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